

Ultra High Performance BGA Cooling Solutions w/ maxiGRIP[™] Attachment

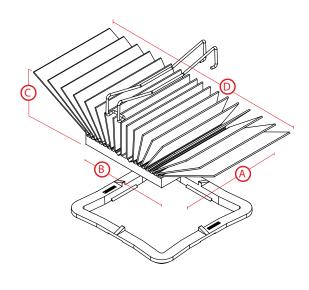
ATS PART # ATS-50250G-C2-R0

Features & Benefits

- maxiFLOW[™] design features a low profile, spread fin » array that maximizes surface area for more effective convection (air) cooling
- maxiGRIP[™] attachment applies steady, even pressure to » the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 » 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- Comes preassembled with high performance, phase » changing, thermal interface material

Thermal Performance

Designed for standard height components from 3 to 4.5mm »





*Image above is for illustration purposes only.

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1.0	5.2	4	
300	1.5	4.1		
400	2.0	3.6		
500	2.5	3.2		
600	3.0	2.9		
700	3.5	2.7		
800	4.0	2.6		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
25 mm	25 mm	12.5 mm	44.9 mm	SAINT-GOBAIN C1100F	BLUE-ANODIZED

NOTES:

- 2) ATS-50250G-C1-R0 is a subsitute item available utilizing an equivalent phase change material (Chomerics T766).
- Thermal performance data are provided for reference only. Actual performance may vary 3) by application.
- 4) ATS reserves the right to update or change its products without notice to improve the design or performance.
- Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT250 5)
- Contact ATS to learn about custom options available. 6)



For more information, to find a distributor or to place an order, visit www.gats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe)

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 $[\]mathbb{W}_{\mathbb{W}}$ Dimension $\mathcal{G}_{\mathbb{F}}$ heat sink height from bottom of the base to the top of the fin field.